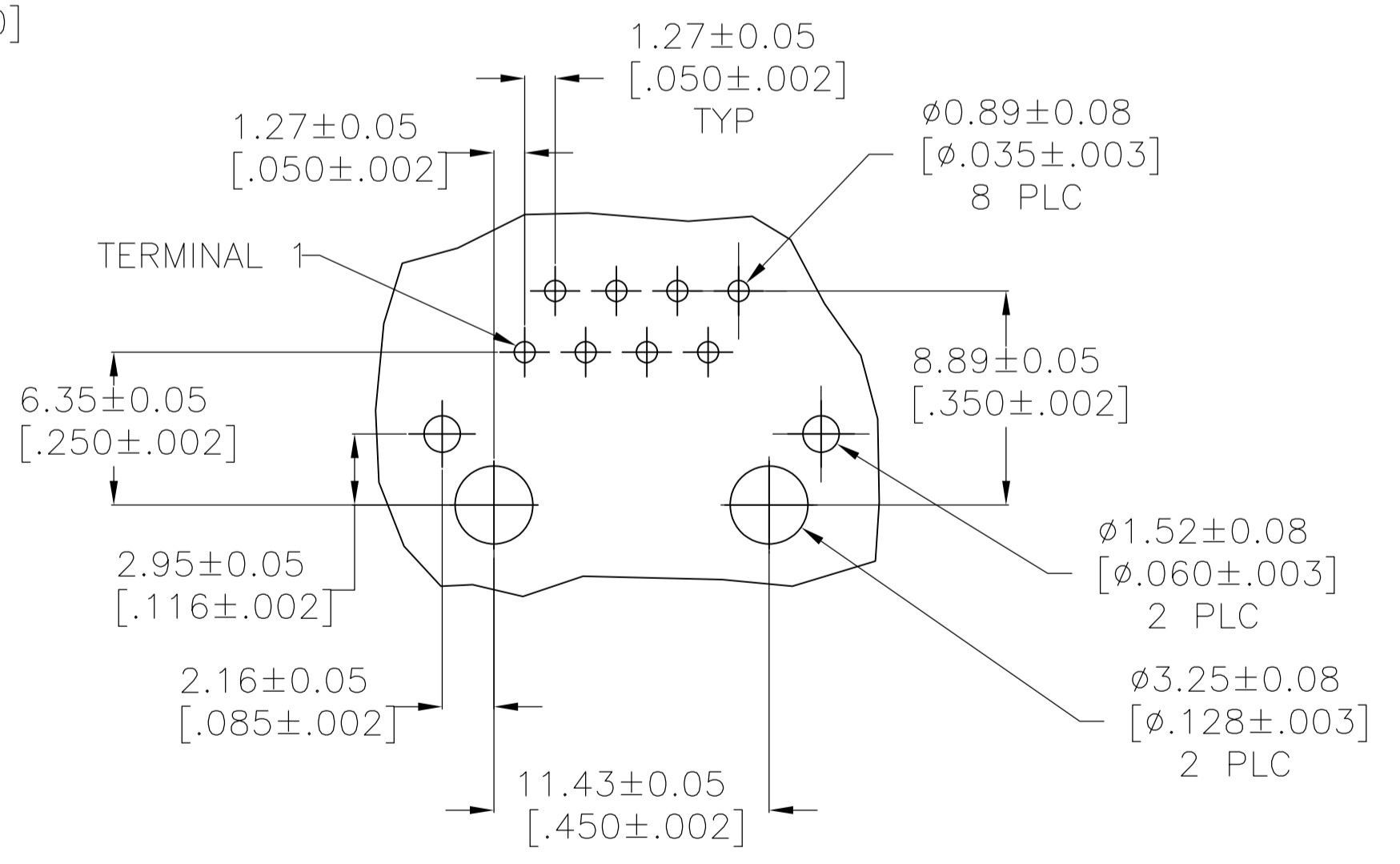
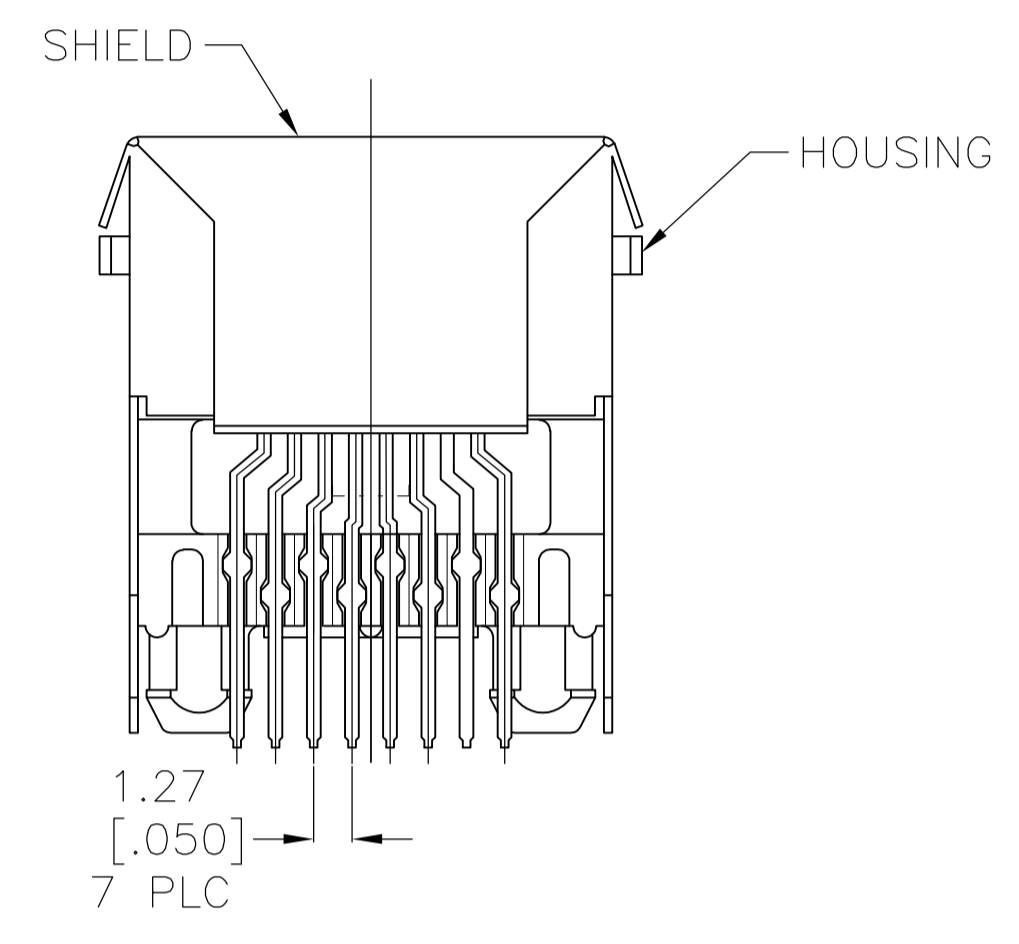
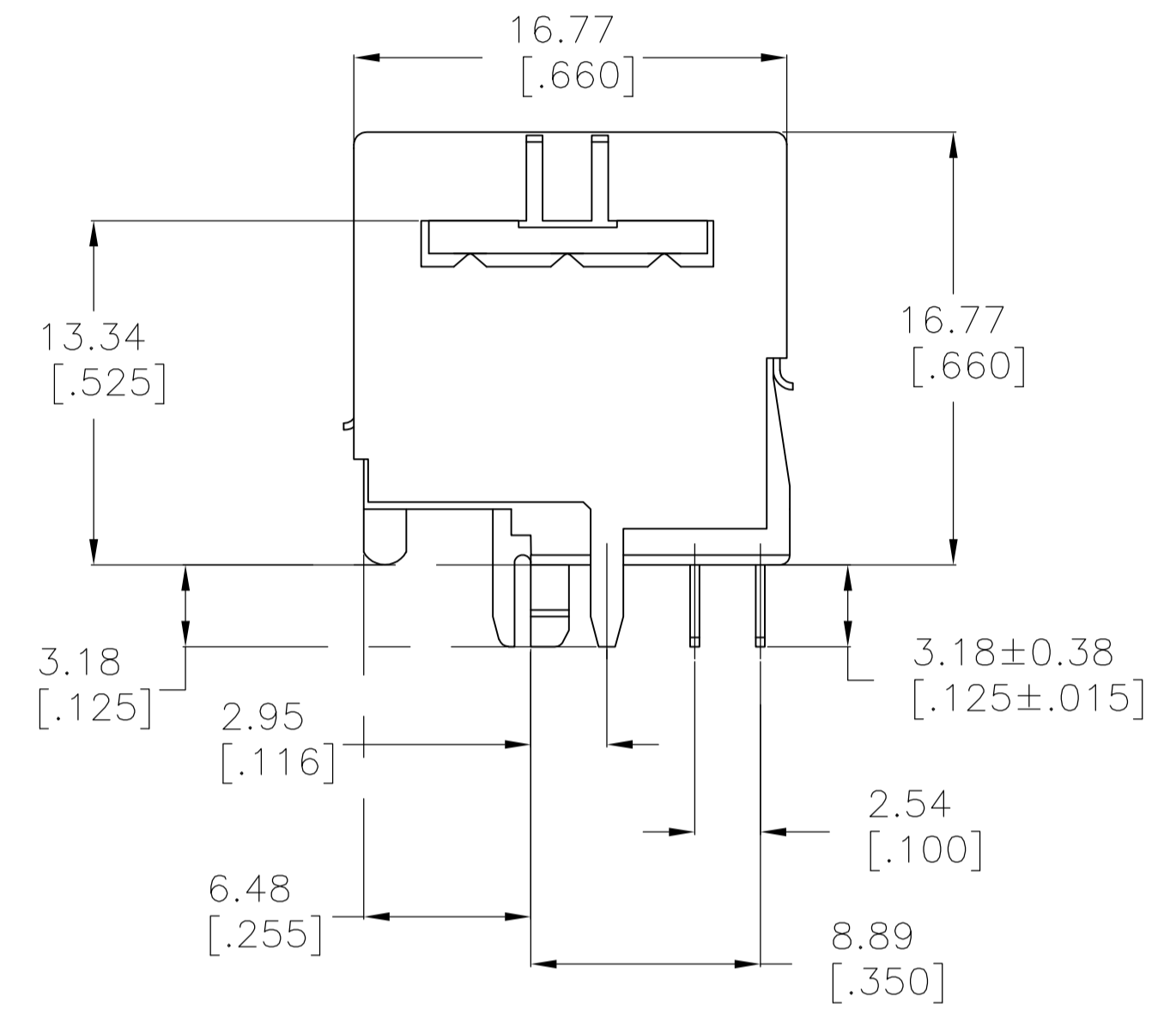
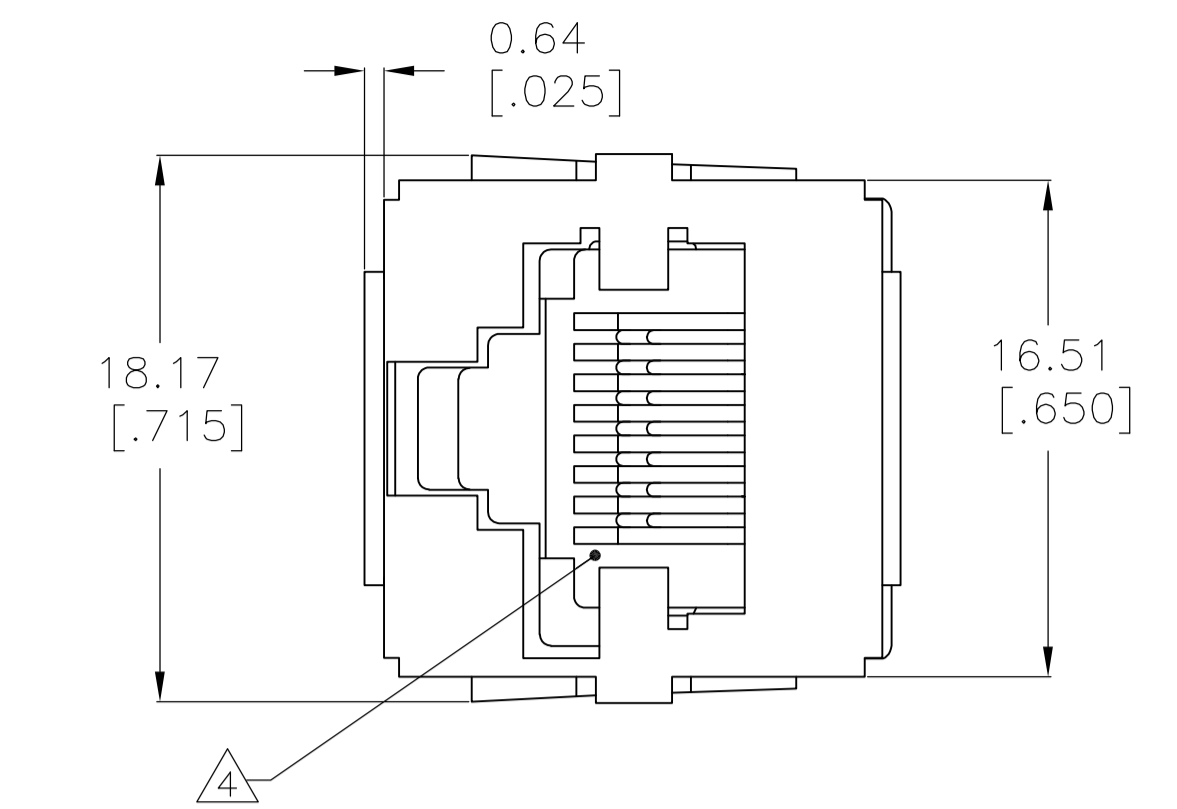
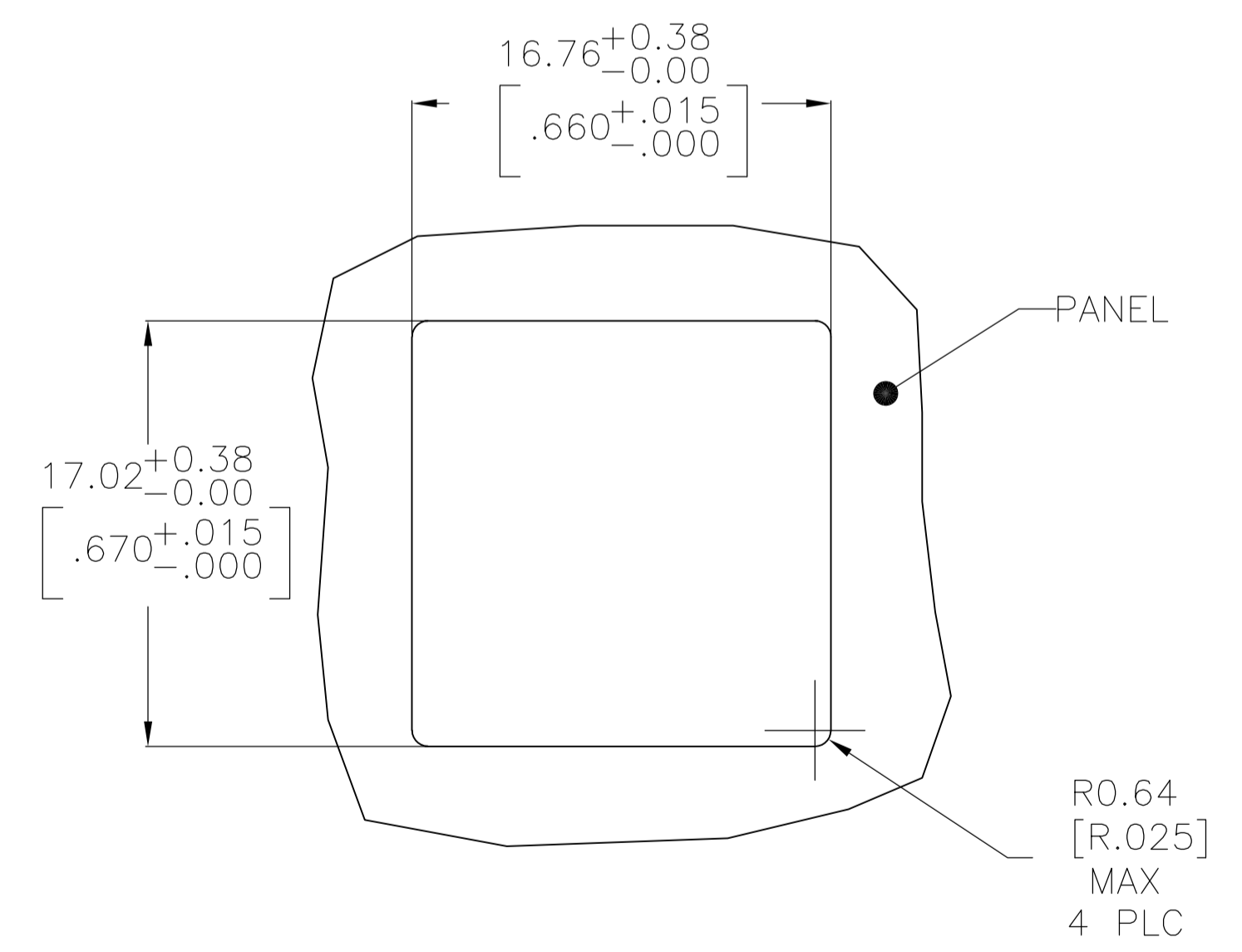


LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION	DATE	DMN	APVD		
C1		REVISED PER ECO-11-005140	02APR11	RK	HMR		



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- MATERIAL:
HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

5557730-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN 0. STRAUSSER/LA. MAYER 22APR2005		STE TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK: J. WESTMAN 22APR2005		NAME: S. FLICKINGER 22APR2005	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: S. FLICKINGER 22APR2005		PRODUCT SPEC: 108-1163	
0 PLC ± -		APPLICATION SPEC: 114-2048		SIZE: A1	
1 PLC ± -		WEIGHT: -		CAGE CODE: 00779	
2 PLC ± -		CUSTOMER DRAWING		SCALE: 4:1	
3 PLC ± 0.13(.005)		SHEET: 1 OF 1		REV: C1	
4 PLC ± -					
ANGLES ± -					
MATERIAL: SEE NOTE 1		FINISH: SEE NOTE 1			